

# LTspice Model

## Logic IC

### TI

## CD4052BNSR

### Model Information

**Model** An original macro model  
**Call Name** MDC\_CD4052BNSR\_LT  
**Pin Assign** 1:Ch\_Y0 2:Ch\_Y2 3:Y\_com 4:Ch\_Y3 5:Ch\_Y1 6:INH 7:VEE 8:VSS 9:B 10:A 11:Ch\_X3 12:Ch\_X0  
 13:X\_com 14:Ch\_X1 15:Ch\_X2 16:VDD  
**File List** Model Library MDC\_CD4052BNSR\_LT01.lib  
 Model Report MDC\_CD4052BNSR\_LT.pdf (this file)  
**Verified Simulator Version** LTspice version XVII  
**Note**

### References

The information which was used for modeling is as follow:

[Data Sheet]

- Date/Version Unknown
- Product name CD4052BNSR
- Company name Texas Instruments Inc.
- Characteristics X-Func-IN,X-Func-OUT,Y-Func-IN,Y-Func-OUT, Signal Input to Output,Address-to-Signal OUT, Inhibit-to-Signal OUT Turning ON, Inhibit-to-Signal OUT Turning OFF

### Simulation Condition

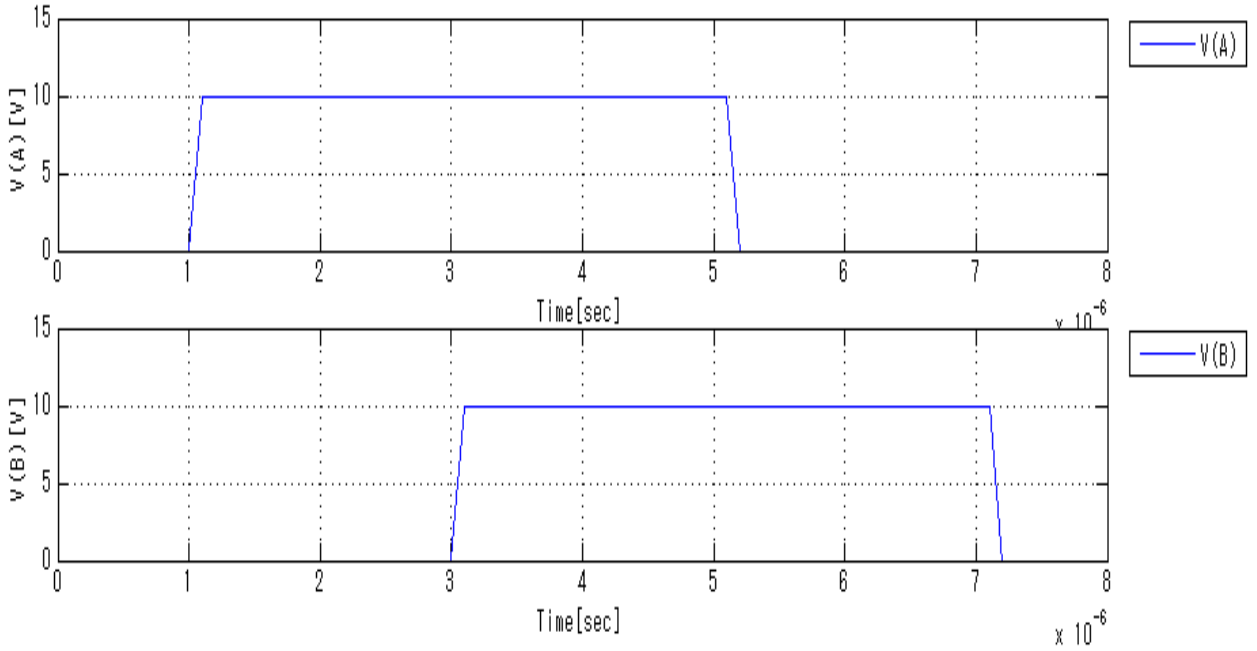
This table shows the value of evaluated simulation condition that was not occurs any convergence problems in this area.

Item	Condition	Unit
Temperature	25	deg C

Simulation results are following.  
Explanatory notes — : simulated

**X-Func-AddressIN**

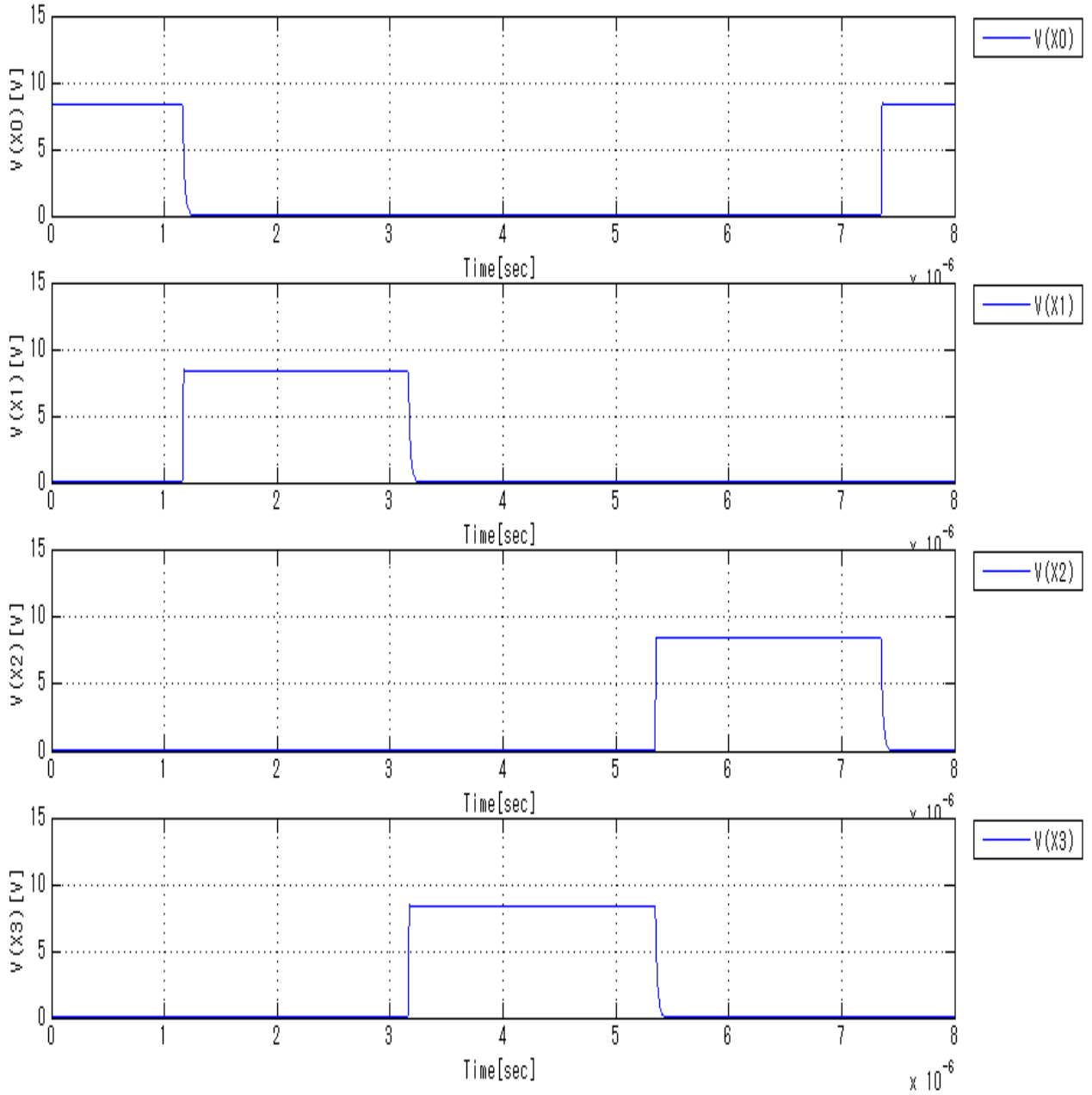
Temp. = 25deg C XCOM=10 V



Simulation results are following.  
Explanatory notes — : simulated

**X-Func-OUT**

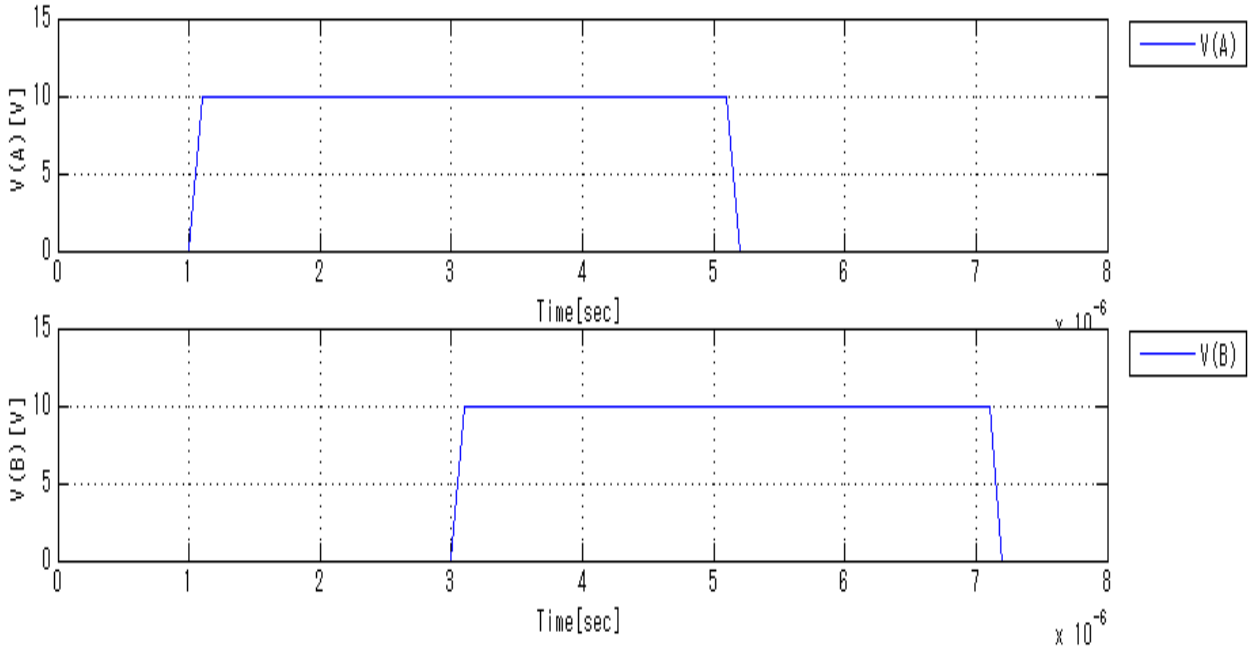
Temp. = 25deg C XCOM=10 V



Simulation results are following.  
Explanatory notes — : simulated

**Y-Func-AddressIN**

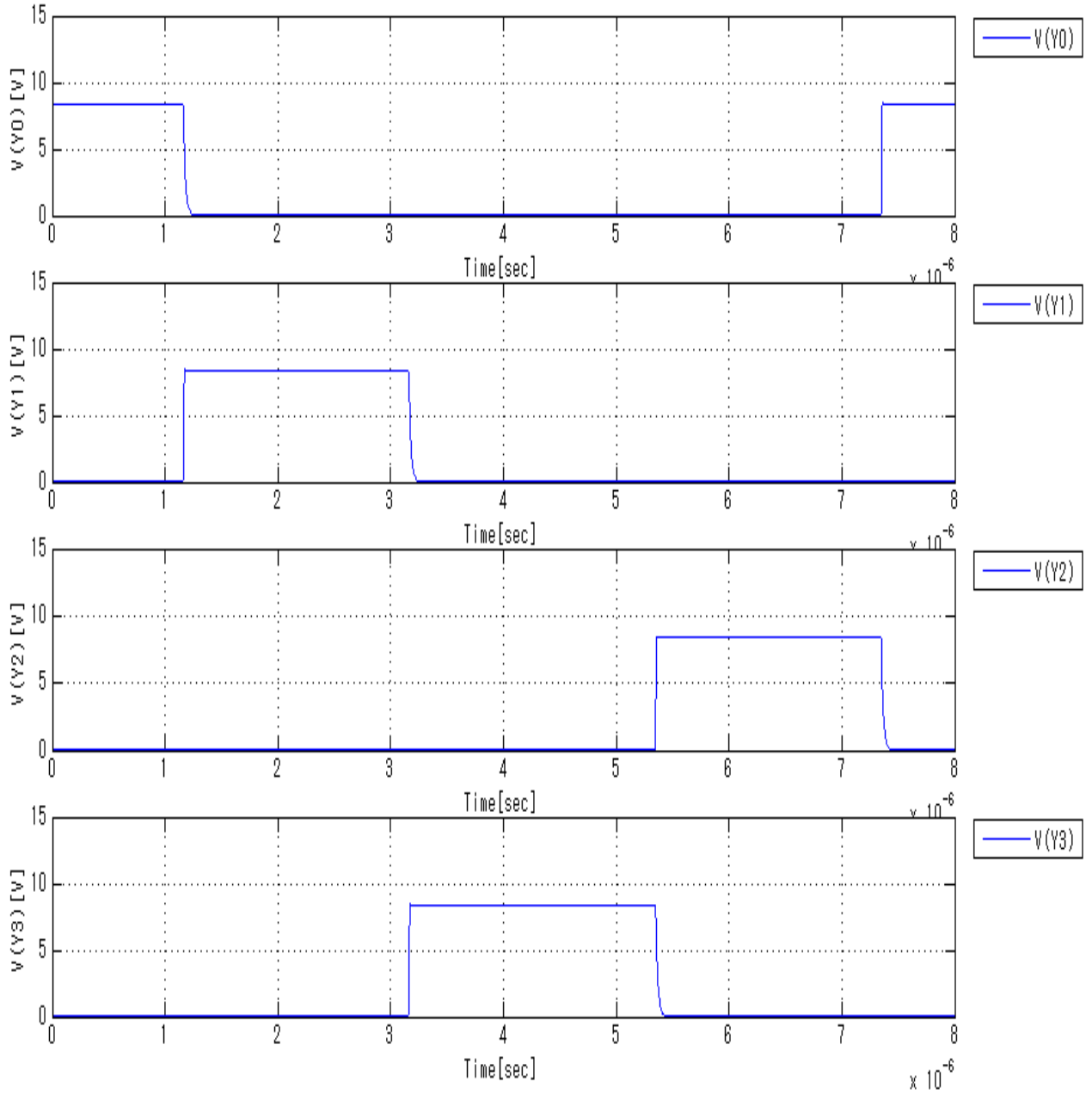
Temp. = 25deg C YCOM=10 V



Simulation results are following.  
Explanatory notes — : simulated

**Y-Func-OUT**

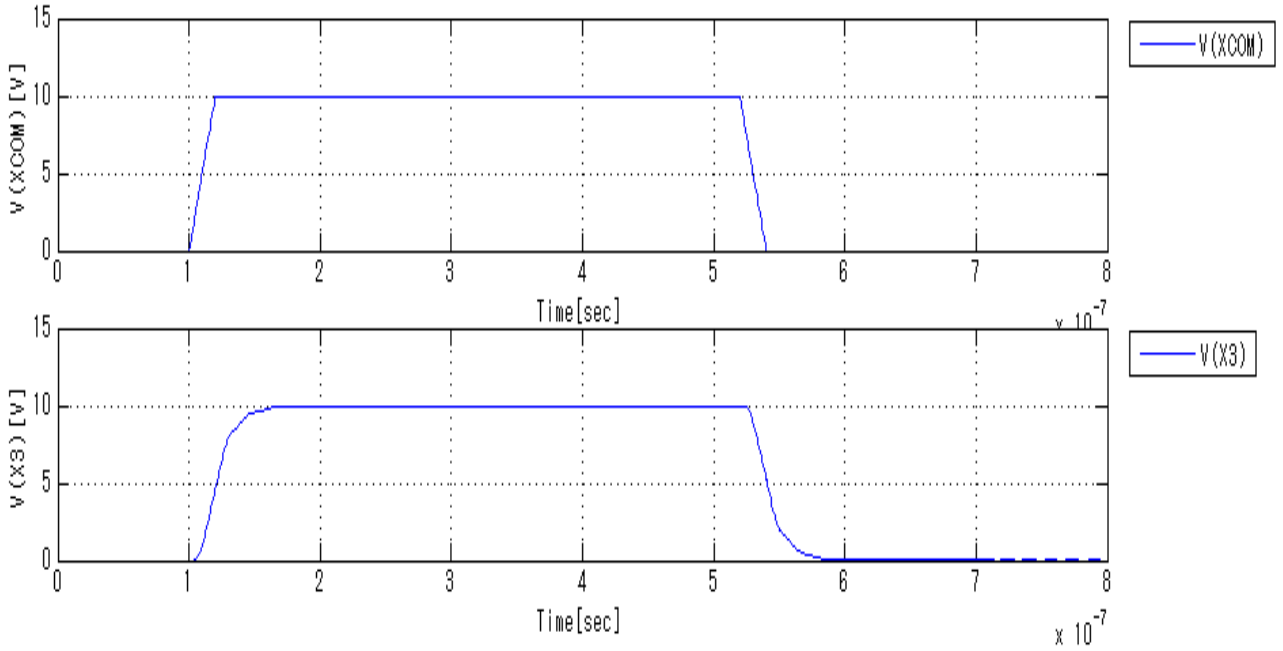
Temp. = 25deg C YCOM=10 V



Simulation results are following.  
Explanatory notes — : simulated

**Signal Input to Output**

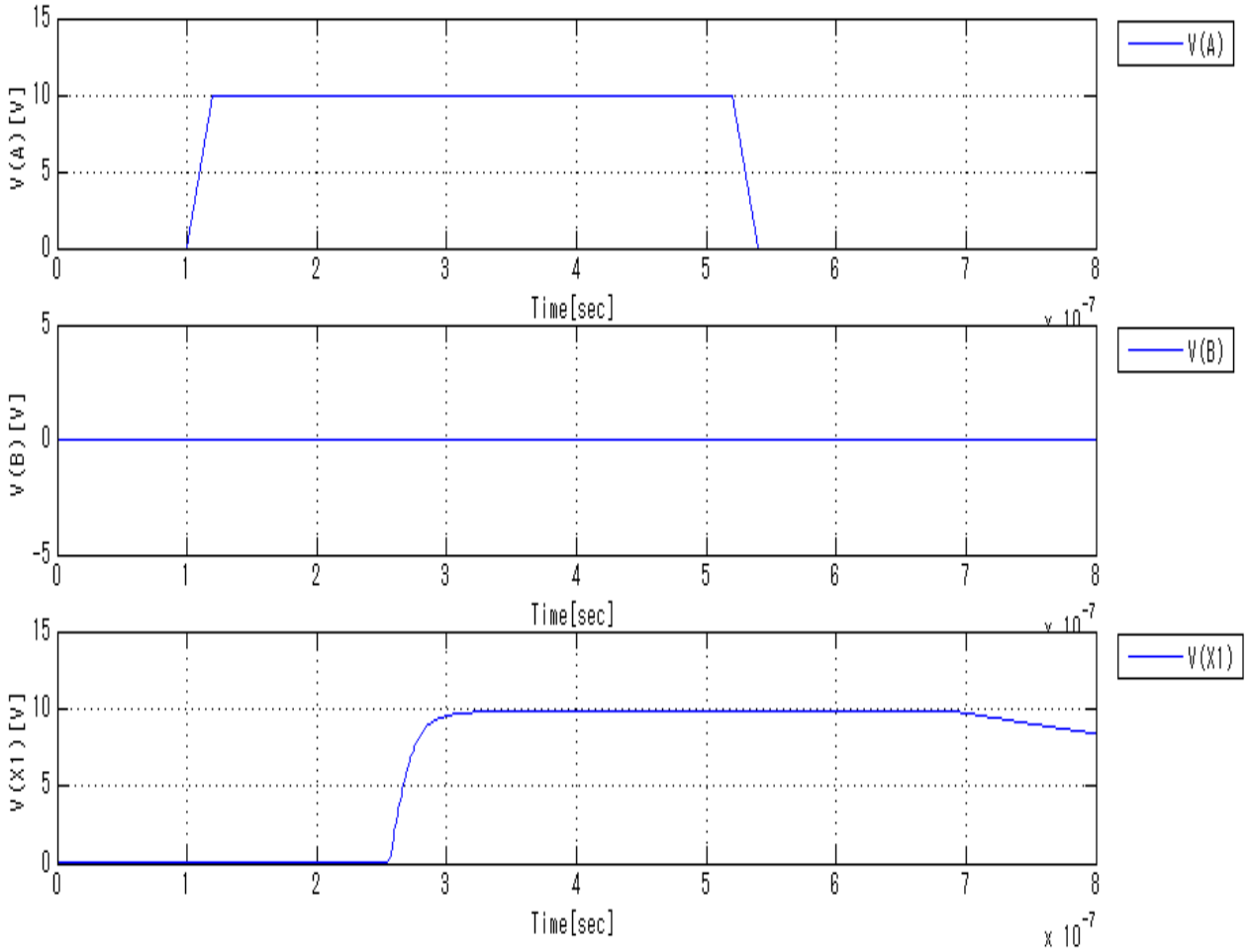
Temp. = 25deg C



Simulation results are following.  
Explanatory notes — : simulated

**Address-to-Signal OUT**

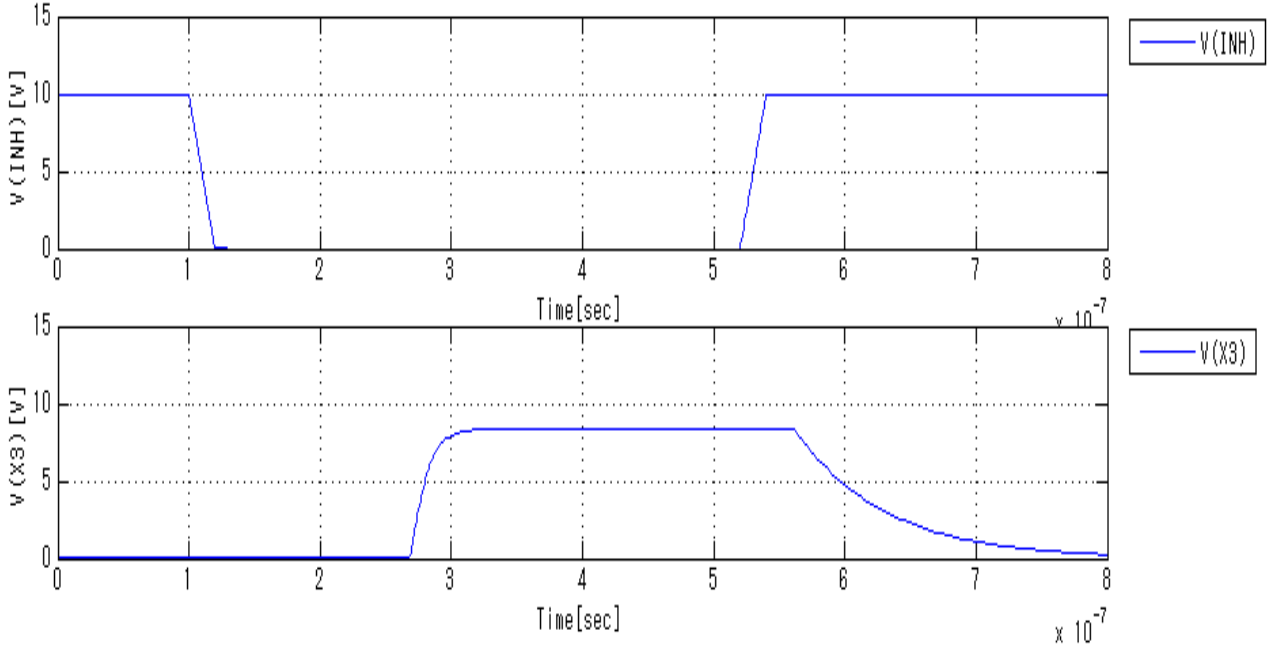
Temp. = 25deg C



Simulation results are following.  
 Explanatory notes — : simulated

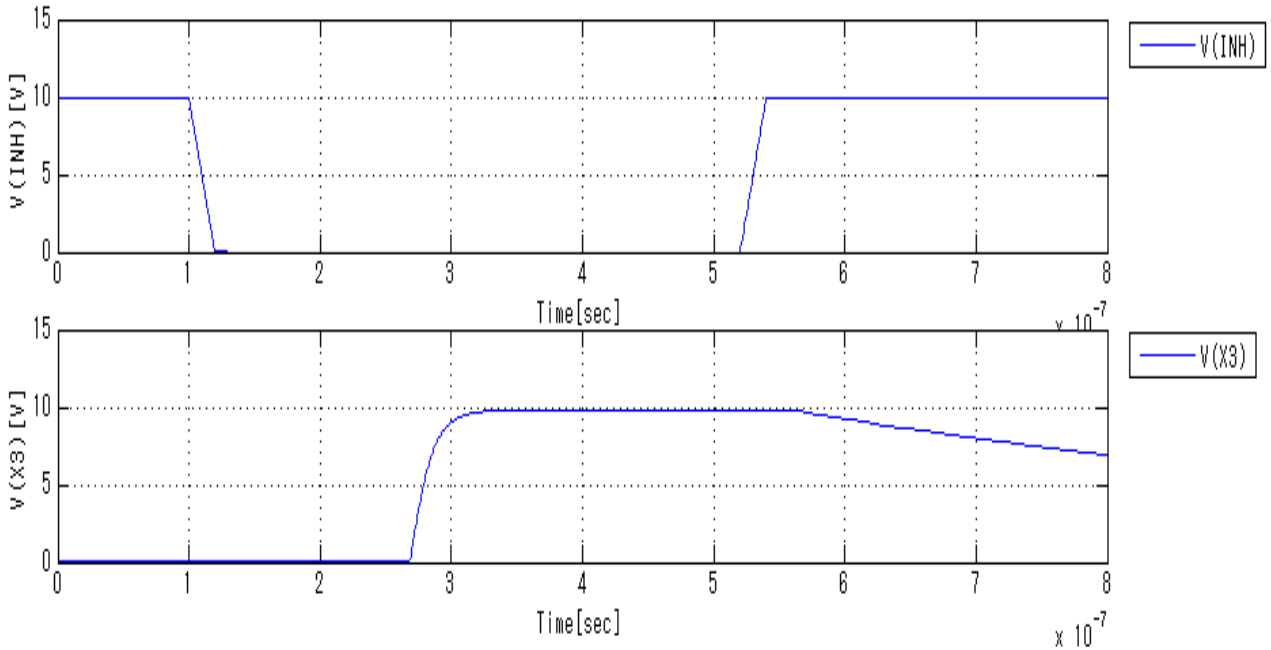
**Inhibit-to-Signal OUT Turning ON**

Temp. = 25deg C



**Inhibit-to-Signal OUT Turning OFF**

Temp. = 25deg C





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